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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



### Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









# **PSE Technology Corporation**

### SPECIFICATION FOR APPROVAL

CUSTOMER	
NOMINAL FREQUENCY	32.768 KHz
PRODUCT TYPE	TYPE G9 SMD CRYSTAL
SPEC. NO. ( P/N )	G93270001
CUSTOMER P/N	
ISSUE DATE	Jan.8,2014
VERSION	С

APPROVED	APPROVED PREPARED			
Brenda	Clame	Bedayeri		
APPROVED BY	AVL Status			
Please return one copy				

### **PSE Technology Corporation**

No.2, Tzu-Chiang 5th Rd, Chung Li Industrial Park, Chung Li City, Taoyuan County, Taiwan (R.O.C.)

TEL: 886-3-451-8888 FAX: 886-3-461-3865

http://www.saronix-ecera.com.tw

\*Pb-free

\*RoHS Compliant

\*HF-Halogen Free

\*REACH Compliant



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3-Oct-11

### **VERSION HISTORY**

Version No.	Version Date	Customer Receipt Date	Supplier Receipt Date	Description	Notes
Α	Apr.18,2011			Initial Release	
В	Oct.3,2011			Changed Operating Temperature Range from -30~70C to -40~85C & Added Shunt Capacitance 7pF	
С	Jan.8,2014			Revised to RoHS Compliant	

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#### **ELECTRICAL SPECIFICATIONS**

SRe Part Number: G93270001

Parameters	Symbol Specifications		Units	Notes
Nominal Frequency	Fn	32.768	KHz	
Frequency Tolerance	FT	± 20	ppm	at 25°C ± 5°C
Load Capacitance	CL	9	pF	Тур.
Drive Level	DL	0.1 / 0.5	μW	Тур / Мах.
Equivalent Series Resistance	ESR	90	ΚΩ	Max.
Temperature Coefficient	K	-0.03	ppm/°C <sup>2</sup>	Тур.
Operating Temperature Range	TR	-40~85	°C	
Shunt Capacitance	C0	7	pF	Max.
Storage Temperature Range		-55~125	°C	
Aging		± 3	ppm	Max 1st year
Insulation Resistance		500	ΜΩ	Min.

#### Reliability ( Mechanical and environmental performances )

No.	Test Items	Conditions	Requirements			
1	Bending test	Apply pressure in the direction of the arrow at a rate of about 0.5mm/s until bent width reaches 5mm, and hold for 30 seconds.	Without mechanical damage such as breaks and satisfy sealing specification.     Frequency change: Within ±5ppm			
2	Shear test	A static load of 20N(2.04kgf) using a R0.5 scratch tool, shall be applied on the core of the component and in the direction of the arrow and held for 5 seconds.	• Equivalent series resistance(E.S.R) change: Within 5kΩ			
3	Core body strength	A static load of 10N(1.02kgf) using a R0.5 pressure rod shall be applied to the center in the direction of the arrow and held for 10 seconds.				
4	Vibration	Endurance conditioning by a frequency sweep shall be made. The entire frequency range, from 10Hz to 55Hz and return to 10Hz, shall be transversed in 1 minute. Amplitude (total excursion): 1.5mm, This motion shall be applied for a period of 2 hours in each of 3 mutually perpendicular axes (a total of 6 hours). For other procedures, refer to JIS C 60068-2-6.				
5	Shock	Peak acceleration: 9810m/s2 - Duration of the pulse: 1ms, Three successive shock shall be applied 3 times perpendicular axes. For other procedures, refer to JIS C 60068-2-27.				

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6	Cold	Quartz crystal units shall be stored in the -40±3°C atmosphere for 1000 hours. Other procedures conform to JIS C 60068-2-1.					orm	Frequency change: Within ±5ppm     Equivalent series resistance(E.S.R) change: Within 5kΩ
7	Dry heat	Quartz crystal units shall be stored in the 100±2°C atmosphere for 100 hours. Other procedures conform to JIS C 60068-2-2.					rm to	After conditioning, quartz crystal units shall be subjected to standard atmospheric conditions for 1 hour, and measured.
8	Damp heat	Quartz crystal units shall be stored in the 40±2°C atmosphere with 90 to 95% relative humidity for 1000 hours. Other procedures conform to JIS C 60068-2-3.						
9	Change of temperature	Quartz crystal units shall be subjected successively 100 cycles of temperature change shown below. Other procedures conform to JIS C 0025.						
			1 2 3 4	Temperatur -40±3°C Normal tempera 100±2°C Normal tempera	ture	Duration 30min. Within 30 sec. 30min. Within 30 sec.		
10	Sealing	Both the test methods specified below shall be applied.  Quartz crystal units shall be soaked in 90°C or higher temperature hot water for 5 minutes.  Quartz crystal units shall be tested by Mass spectrometric leakage detector to measure the leakage					er	Without repetitive leaking bubbles from quartz crystal units.      1×10-9 Pa·m3/s or less
11	Aging	rate of helium gas.  Quartz crystal units shall be stored in the 85±3°C atmosphere for 720±12 hours.				ed in the 85±3℃		<ul> <li>Frequency change: Within ±5ppm</li> <li>Equivalent series resistance(E.S.R) change: Within 5kΩ</li> <li>After conditioning, quartz crystal units shall be subjected to standard atmospheric conditions for 1 hour, and measured.</li> </ul>
12	Solder-ability	Terminals coated with flux shall be immersed in the solder bath for 3.5±0.5 seconds.						Minimum 95% of immersed terminal shall be covered with new uniform solder.
		l		Items		Conditions		
			1	Solder	Sn-3.	.0Ag-0.5Cu		
			2	Flux	meth	oximately 25wt% anol(JIS K 8891) on of resin(JIS K ).		
			3	Solder temperature	255±	5℃		

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Reflow soldering method Resistance to soldering heat 温度プロファイル Temperature profile はんだ付け Soldering 260 Soldering temperature 220 徐冷(常温自然放置) 予熱 Slow cooling(Stored Pre-heating at room temperature) 160 Within 5s  $90 \pm 10s$ • Frequency change: Within ±5ppm Peak temperature: 260±5° for within 5seconds. • Equivalent series resistance (E.S.R) Soldering temperature: 220°C or higher for 60±10 change: Within 10kΩ seconds. · After conditioning, quartz crystal units Pre-heating temperature: 160±10°C for 90±10 seconds shall be subjected to standard atmospheric Quartz crystal units which is put on PCB shall be conditions for 1 hour, and measured. through reflow soldering furnace twice with the condition · Without distinct deformation in shown above. appearance. Soldering iron method • Frequency change: Within ±5ppm Terminals shall be applied 400±10℃ soldering iron heat • Equivalent series resistance(E.S.R) for 3.5±0.5 seconds twice. change: Within 5kΩ After conditioning, quartz crystal units shall be subjected to standard atmospheric conditions for 1 hour, and measured. · Without distinct deformation in appearance. Solubility to Soak cleaning • Without mechanical damage such as breaks and satisfy sealing specification. resistance Quartz crystal units shall be soaked in isopropyl alcohol at normal temperature for 90 • Frequency change: Within ±5ppm seconds. • Equivalent series resistance(E.S.R)

change: Within 5kΩ

appearance.

· Without distinct deformation in

· Marking shall be legible.

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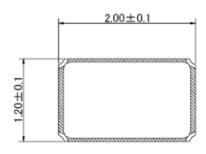
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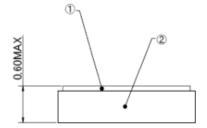
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#### **Marking**

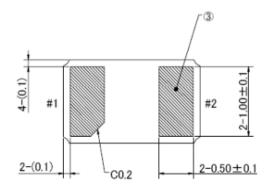


#### **Dimensions** (Units: mm)

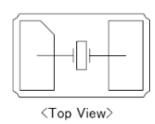




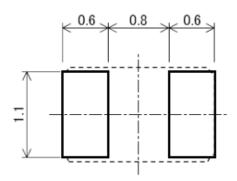




内部接続図 Internal connection



#### Land dimensions(unit: mm)

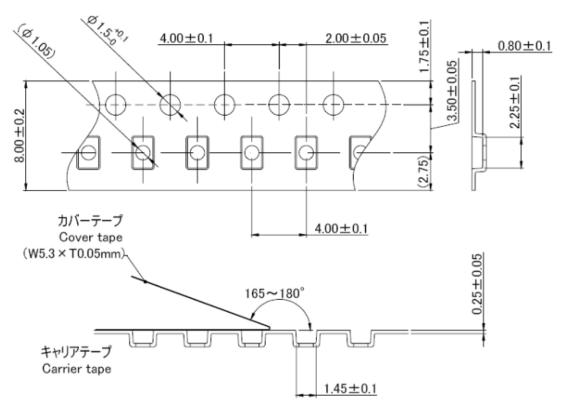


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#### **TAPING**



#### **REEL**

Reel

